

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An apparatus comprising:
a plurality of devices formed on a substrate; and
a scribe line area separating each of the plurality of devices; and
a masking material overlying a portion of the scribe line area so that an interface between the masking material and the substrate exists at the substrate surface, the masking material having a thickness across the scribe line area that is equal to and defined by the step height of the plurality of devices, wherein process operations of material removal are completed and the apparatus is in a condition to be singulated.
2. (Original) The apparatus of claim 1, wherein the masking material is transparent.
3. (Original) The apparatus of claim 1, wherein the masking material comprises an acrylate moiety.
4. (Cancelled)
5. (Currently Amended) The apparatus of claim 1, wherein the plurality of devices comprise as one material layer a material comprising one of a colorant.
6. (Original) The apparatus of claim 5, wherein the colorant comprises a pigment.
7. (Original) The apparatus of claim 1, wherein the plurality of devices each comprise a sensor portion.
8. (Original) The apparatus of claim 1, wherein the masking material overlies the entire portion of the scribe line area adjacent the plurality of devices.
9. (Original) The apparatus of claim 6, wherein the masking material comprises a plurality of discrete structures occupying less than the entire portion of the scribe line area adjacent the plurality of devices.

10. (Currently Amended) A semiconductor wafer comprising:
a plurality of integrated circuits formed on the wafer, each integrated circuit mapped on
the surface of a wafer adjacent a scribe line area; and
a masking material overlying a portion of the scribe line area so that an interface between
the masking material and the substrate exists at the substrate surface, the masking material
having a thickness across the scribe line area that is equal to and defined by the step height of the
plurality of devices, wherein process operations of material removal are completed and the
apparatus wafer is in a condition to be singulated.

11. (Original) The semiconductor wafer of claim 10, wherein the masking material is
transparent.

12. (Cancelled)

13. (Currently Amended) The semiconductor wafer of claim 4-claim 10, wherein the
plurality of integrated circuits comprise as one material layer, a material comprising one of a
colorant.

14. (Original) The semiconductor wafer of claim 13, wherein the colorant comprises a
pigment.

15. (Currently Amended) The semiconductor wafer of claim 10, wherein the plurality of
devices-integrated circuits comprise a sensor portion.

16. (Currently Amended) The semiconductor wafer of claim 10, wherein the masking
material overlies the entire portion of the scribe line area adjacent the plurality of devices
integrated circuits.

17. (Currently Amended) The semiconductor wafer of claim 10, wherein the scribe line area
has a width dimension adjacent the plurality of integrated circuits and the masking material

comprises a plurality of discrete structures occupying less than the entire portion-width dimension of the scribe line area.